

Title (en)  
DEVICE FOR MONITORING AND CALIBRATING OXIDE CHARGE MEASUREMENT EQUIPMENT AND METHOD THEREFOR

Title (de)  
APPARAT ZUR KONTROLLE UND KALIBRIERUNG VON OXIDLADUNGSMESSGERÄTEN UND ZUGEHÖRIGE METHODE

Title (fr)  
DISPOSITIF DESTINE A CONTROLER ET A CALIBRER UN EQUIPEMENT DE MESURE DE CHARGE D'OXYDE ET PROCEDE CORRESPONDANT

Publication  
**EP 1274529 A1 20030115 (EN)**

Application  
**EP 00918293 A 20000320**

Priority  
US 0007711 W 20000320

Abstract (en)  
[origin: WO0170438A1] A stabilized wafer for monitoring and calibrating oxide charge test equipment. The stabilized wafer comprises; a silicon wafer, a SiO<sub>2</sub> layer of at least 100 angstroms upon the silicon wafer, and a phosphosilicate glass layer containing phosphorus formed in the SiO<sub>2</sub> layer for providing the stabilized wafer by stabilizing an SiO<sub>2</sub> interface and containing oxygen ions. The stabilized wafer is used for monitoring and calibrating oxide charge test equipment.

IPC 1-7  
**B23B 3/00**

IPC 8 full level  
**H01L 21/66** (2006.01); **H01L 23/544** (2006.01); **G11B 5/39** (2006.01); **H01L 21/316** (2006.01)

CPC (source: EP KR US)  
**B82Y 10/00** (2013.01 - EP); **B82Y 25/00** (2013.01 - EP US); **H01L 22/00** (2013.01 - KR US); **H01L 22/34** (2013.01 - EP); **G11B 5/3903** (2013.01 - EP); **G11B 2005/3996** (2013.01 - EP); **H01L 21/02129** (2013.01 - EP KR US); **H01L 21/02164** (2013.01 - EP KR US); **H01L 21/02337** (2013.01 - US); **H01L 2924/0002** (2013.01 - EP)

Citation (search report)  
See references of WO 0170438A1

Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)  
**WO 0170438 A1 20010927**; AU 3912600 A 20011003; EP 1274529 A1 20030115; JP 2004507878 A 20040311; KR 20020089407 A 20021129

DOCDB simple family (application)  
**US 0007711 W 20000320**; AU 3912600 A 20000320; EP 00918293 A 20000320; JP 2001568682 A 20000320; KR 20027012504 A 20020923